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Judy Paolillo 8/28/03  
(Signature & Date)

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of \_\_\_\_\_: August 28, 2003

Tze-Chiang Chen, et al.: Group Art Unit: 5250

Serial No. Divisional Application of  
10/047,964 \_\_\_\_\_:

Examiner: Roy Karl Potter

Filed: 8/28/2003 \_\_\_\_\_:

International Business Machines Corporation  
2070 Route 52  
Hopewell Junction, NY 12533

**TITLE:** BILAYER HDP CVD/PE CVD CAP IN ADVANCED BEOL INTERCONNECT STRUCTURES  
AND METHOD THEREOF

**INFORMATION DISCLOSURE STATEMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

Pursuant to the duty of disclosure set forth in 37 C.F.R. 1.56, and further pursuant to the provisions of 37 C.F.R. 1.97 and 1.98, applicants hereby respectfully submit copies of the non-US patents and publications as listed on Form PTO-1449, attached hereto.

In citing these documents, no representation is made nor intended as to the pertinency or non-pertinency of the art, that better art than that listed is not available, or that other art is not applicable.

No fee is believed to be due for this submission. If any fees are required, however, the Commissioner is hereby authorized to charge such fees to Deposit Account No. 09-0458.

Respectfully submitted,  
Tze-Chiang Chen, et al.

By Margaret A. Pepper  
Margaret A. Pepper, Attorney  
Registration No. 45,008  
Telephone No. 845-894-4713

# INFORMATION DISCLOSURE CITATION

(Use several sheets if necessary)

ATTY DOCKET NO.

FIS9-2001-0 295-US2

SERIAL NO.

Divisional of  
10/047,964

Tze-Chiang Chen et al.

FILING

8/27/03

GROUP

5250

## U.S. PATENT DOCUMENTS

*EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	6,043,152	03/28/2000	Chang et al.			
	6,080,529	06/27/2000	Ye et al.			
	6,099,701	08/08/2000	Liu et al.			
	6,107,188	08/22/2000	Liu et al.			
	6,127,238	10/03/2000	Liao et al.			
	6,153,523	11/28/2000	Van Ngo et al.			
	6,162,583	12/19/2000	Yang et al.			
	6,211,061 B1	04/03/2001	Chen et al.			
	6,218,732 B1	04/17/2001	Russell et al.			
	6,225,210 B1	05/01/2001	Ngo et al.			
	6,235,633 B1	05/22/2001	Jang			

## FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
	✓	WO 00/19523	06/06/2000	CA,CN,JP, European Patent				
	✓	JP2001015480A	01/19/2001	Japan				
	✓	JP2001053076A	02/23/2001	Japan				
	✓	JP1111843A	04/28/1989	Japan				
		WO 99/33102	07/01/1999	JP,KR, European Patent				

## OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

	✓	Soo Geun Lee et al., "Low Dielectric Constant 3MS a-SiC:H as Cu Diffusion Barrier Layer in Cu Dual Damascene Process," Japanese Journal of Applied Physics, Part 1, Vol. 40, No. 4B, pp. 2663-2668, April 2001.
	✓	R.D. Goldblatt et al., "A High Performance 0.13 um Copper BEOL Technology with Low-k Dielectric," Proceedings of the IEEE 2000 International Interconnect Technology Conference, pp. 261-263, June 5-7, 2000.

EXAMINER

DATE CONSIDERED

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

**INFORMATION DISCLOSURE CITATION**  
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5250

**U.S. PATENT DOCUMENTS**

*EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	6,261,951 B1	07/17/2001	Buchwalter et al.			
	US 2001/0000155 A1	04/05/2001	Huang et al.			
	US 2001/0002333 A1	05/31/2001	Huang et al.			
	US 2001/0002731 A1	06/07/2001	Ueda			
	US 2001/0003064 A1	06/07/2001	Ohto			
	6,265,779	07/24/01	Grill, et al.			
	6,441,491	08/27/02	Grill, et al.			

**FOREIGN PATENT DOCUMENTS**

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO

**OTHER DOCUMENTS** (Including Author, Title, Date, Pertinent Pages, Etc.)

		✓	J. Yota et al., "Comparison Between HDP CVD and PECVD Silicon Nitride for Advanced Interconnect Applications," Proceedings of the IEEE 2000 International Interconnect Technology Conference, pp. 76-78, June 5-7, 2000.

EXAMINER

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